Part Number: XZUR55W-2

3.2x1.6mm SMD CHIP LED LAMP

Features

• Ideal for indication light on hand held products

• Long life and robust package

• Variety of lens types and color choices available

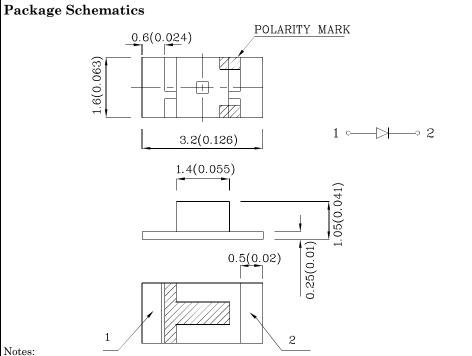
ullet Package : 2000 pcs / reel

• Moisture sensitivity level : level 3

• RoHS compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings $(T_A=25^{\circ}C)$		UR (GaAsP/ GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	160	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		

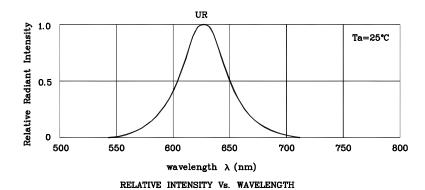
Operating Characteristics (T _A =25°C)		UR (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission (Typ.) $(I_F=20 \text{mA})$	λΡ	627	nm
Wavelength of Dominant Emission (Typ.) $(I_F=20 \text{mA})$	λD	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

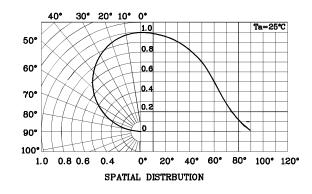
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous} \\ \text{Intensity} \\ \text{(I}_F = 20 \text{mA)} \\ \text{mcd} \end{array}$		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZUR55W-2	Red	GaAsP/GaP	Water Clear	8	14	627	120°

Apr 15,2011 XDSA1337 V7 Layout: Maggie L.

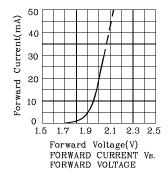


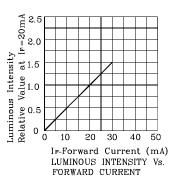


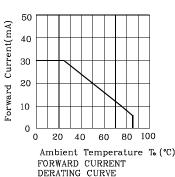


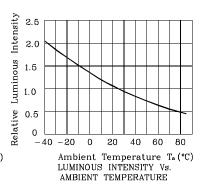


UR



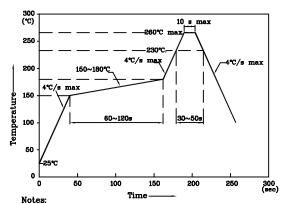






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

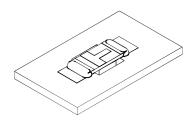


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

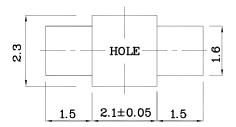




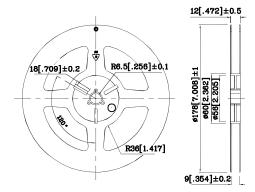
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



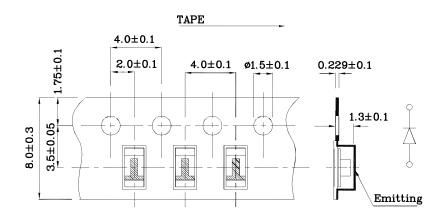
❖ Recommended Soldering Pattern (Units:mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

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- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XDSA1337 V7 Layout: Maggie L.





PACKING & LABEL SPECIFICATIONS

